

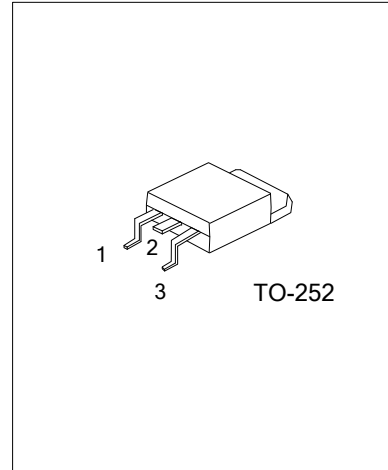
**N-Channel Power MOSFET**

● **Description**

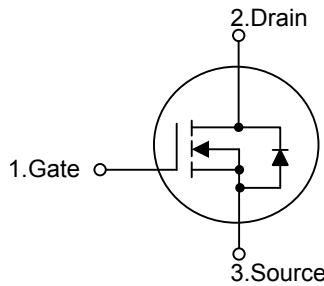
The FL12N10 is an N-channel mode power MOSFET using UTC's advanced technology to provide customers with minimum on-state resistance for extremely high dense cell design, rugged avalanche characteristics and less critical alignment steps .

● **Features:**

- \*  $R_{DS(on)} < 0.10\Omega @V_{GS} = 10 V$
- $R_{DS(on)} < 0.12\Omega @V_{GS} = 5.0 V$
- \* High switching speed
- \* Low gate charge



**SYMBOL**



● **ORDERING INFORMATION**

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
12N10L-TN3-R	12N10G-TN3-R	TO-252	G	D	S	Tape Reel
12N10L-TN3-T	12N10G-TN3-T	TO-252	G	D	S	Tube

<p>12N10L-TN3-R</p> <p>(1)Packing Type</p> <p>(2)Package Type</p> <p>(3)Lead Free</p>	<p>(1) R: Tape Reel, T: Tube</p> <p>(2) TN3: TO-252</p> <p>(3) G: Halogen Free, L: Lead Free</p>
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## N-Channel Power MOSFET

● **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage ( $V_{GS}=0$ )		$V_{DSS}$	100	V	
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V	
Drain Current	Continuous	$I_D$	$T_C = 25^\circ\text{C}$	12	A
			$T_C = 100^\circ\text{C}$	8.5	A
	Pulsed (Note 2)		$I_{DM}$	48	A
Power Dissipation			30	W	
Derating Factor		$P_D$	0.2	W/ $^\circ\text{C}$	
Avalanche Energy (Note 3)		$E_{AS}$	100	mJ	
Junction Temperature		$T_J$	+150	$^\circ\text{C}$	
Storage Temperature		$T_{STG}$	-55 ~ +150	$^\circ\text{C}$	

Note: 1 Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Pulse width limited by safe operating area

3. Starting  $T_J = 25^\circ\text{C}$ ,  $I_D = 12\text{A}$ ,  $V_{DD} = 50\text{V}$

● **THERMAL DATA**

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	$\theta_{JA}$	100	$^\circ\text{C}/\text{W}$
Junction to Case	$\theta_{JC}$	5	$^\circ\text{C}/\text{W}$

● **ELECTRICAL CHARACTERISTICS** ( $T_C=25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>OFF CHARACTERISTICS</b>							
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=250\mu\text{A}$ , $V_{GS}=0\text{V}$	100			V	
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=\text{Max rating}$ , $V_{GS}=0\text{V}$			1	$\mu\text{A}$	
Gate- Source Leakage Current	$I_{GSS}$	Forward			+100	nA	
		Reverse			-100	nA	
<b>ON CHARACTERISTICS</b>							
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1		3	V	
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$ , $I_D=6\text{A}$		0.15	0.18	$\Omega$	
<b>DYNAMIC PARAMETERS</b>							
Input Capacitance	$C_{ISS}$	$V_{GS}=0\text{V}$ , $V_{DS}=25\text{V}$ , $f=1.0\text{MHz}$		430		pF	
Output Capacitance	$C_{OSS}$				90		pF
Reverse Transfer Capacitance	$C_{RSS}$				20		pF

● **ELECTRICAL CHARACTERISTICS(Cont.)**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SWITCHING PARAMETERS</b> (Note 1,2)						
Total Gate Charge	$Q_G$	$V_{GS}=10\text{V}$ , $V_{DD}=80\text{V}$ , $I_D=12\text{A}$		7.5	10	nC
Gate to Source Charge	$Q_{GS}$			2.5		nC
Gate to Drain Charge	$Q_{GD}$			3.0		nC
Turn-ON Delay Time	$t_{D(ON)}$	$V_{DD}=30\text{V}$ , $I_D=1\text{A}$ , $R_G=9.1\Omega$ , $V_{GS}=10\text{V}$ (Fig. 1)		12	24	ns
Rise Time	$t_R$			7	14	ns
Turn-OFF Delay Time	$t_{D(OFF)}$			18	35	ns
Fall-Time	$t_F$			3	6	ns
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Maximum Body-Diode Continuous Current	$I_S$				12	A
Maximum Body-Diode Pulsed Current	$I_{SM}$				48	A
Drain-Source Diode Forward Voltage (Note 1)	$V_{SD}$	$I_S=12\text{A}$ , $V_{GS}=0\text{V}$			1.2	V

Notes: 1. Pulsed: pulse duration=300 $\mu\text{s}$ , duty cycle 1.5%

2. Essentially independent of operating temperature